



CHENMKO ENTERPRISE CO.,LTD

Halogens free devices

SURFACE MOUNT

SCHOTTKY BARRIER RECTIFIER

VOLTAGE RANGE 20 - 40 Volts CURRENT 1.0 Ampere

SSM5817SAGP

THRU

SSM5819SAGP

FEATURES

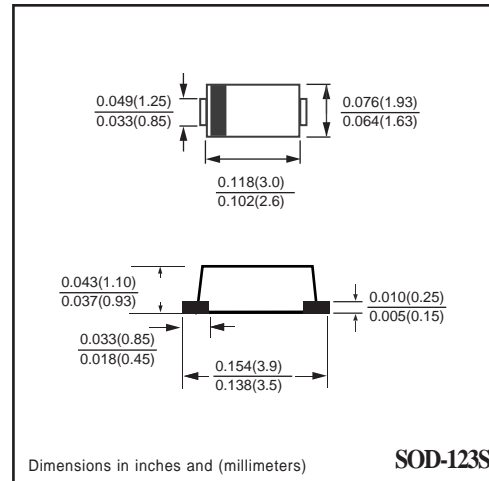
- * Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- * For surface mounted applications
- * Low profile package
- * Built-in strain relief
- * Metal silicon junction, majority carrier conduction
- * Low power loss, high efficiency
- * High current capability, low forward voltage drop
- * High surge capability
- * For use in low voltage high frequency inverters, free wheeling, and polarity protection applications
- * High temperature soldering guaranteed : 260°C/10 seconds at terminals
- * Lead free devices

MECHANICAL DATA

Case: JEDEC SOD-123S molded plastic
Terminals: Solder plated, solderable per MIL-STD-750, Method 2026
Polarity: Color band denotes cathode end



SOD-123S



SOD-123S

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.
 Single phase, half wave, 60 Hz, resistive or inductive load.
 For capacitive load, derate current by 20%.

MAXIMUM RATINGS (At TA = 25°C unless otherwise noted)

RATINGS	SYMBOL	SSM5817SAGP	SSM5818SAGP	SSM5819SAGP	UNITS
Maximum Recurrent Peak Reverse Voltage	VRRM	20	30	40	Volts
Maximum RMS Voltage	VRMS	14	21	28	Volts
Maximum DC Blocking Voltage	VDC	20	30	40	Volts
Maximum Average Forward Rectified Current at TL = 90°C	Io	1.0			Amps
Peak Forward Surge Current 8.3 ms single half sine-wave superimposed on rated load (JEDEC method) TL = 70°C	IFSM	25			Amps
Typical Junction Capacitance (Note 2)	CJ	110			pF
Typical Thermal Resistance (Note 1)	R θJL	80			°C / W
Storage and Operating Temperature Range	TJ, TSTG	-65 to +125			°C

ELECTRICAL CHARACTERISTICS (At TA = 25°C unless otherwise noted)

CHARACTERISTICS	SYMBOL	SSM5817SAGP	SSM5818SAGP	SSM5819SAGP	UNITS
Maximum Instantaneous Forward Voltage at 1.0 A DC	VF	0.45	0.55	0.60	Volts
Maximum Average Reverse Current at Rated DC Blocking Voltage	@ TA = 25°C	1.0			mAmps
	@ TA = 100°C	10			mAmps

NOTES : 1. Thermal Resistance (Junction to Lead) : PC Board Mounted on 0.2 X 0.2" (5 X 5mm) copper pad area.
 2. Measured at 1.0 MHz and applied reverse voltage of 4.0 volts
 3. ESD sensitive product handling required.

RATING CHARACTERISTIC CURVES (SSM5817SAGP THRU SSM5819SAGP)

FIG. 1 - TYPICAL FORWARD CURRENT DERATING CURVE

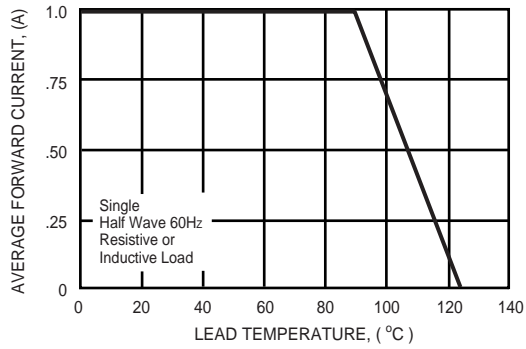


FIG. 2 - TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

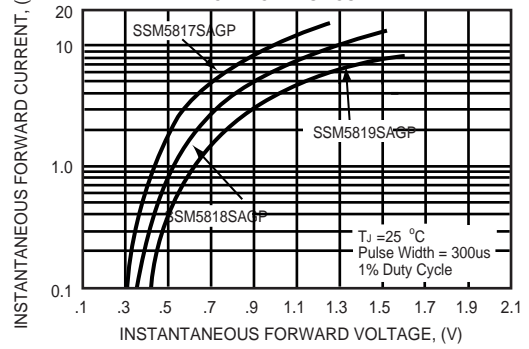


FIG. 3 - TYPICAL REVERSE CHARACTERISTICS

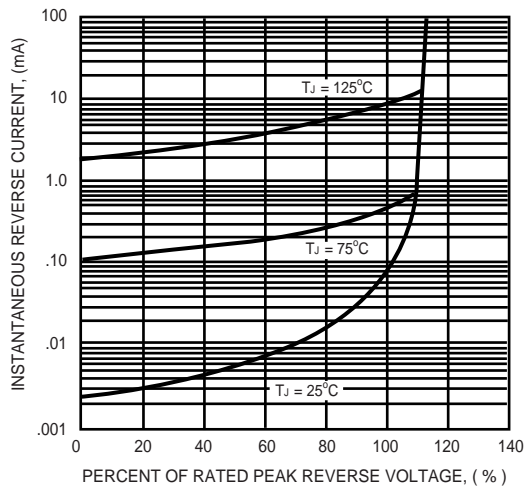


FIG. 4 - MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

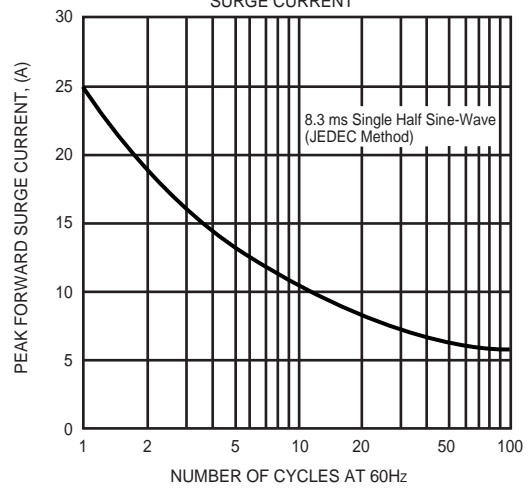


FIG. 5 - TYPICAL JUNCTION CAPACITANCE

